

IN THE SPECIFICATION:

Please amend Page 5, Lines 6-16, [Paragraph 0011] as follows:

One advantageous embodiment of the present invention comprises a structure for receiving a ball bond. The structure comprises substrate material that has portions that form a substrate cavity. The structure also comprises [[and]] a wire bond pad metal that covers and fills the substrate cavity. The wire bond pad also has portions that form a wire bond cavity for receiving the ball bond. When a ball on the end of a wire is wirebonded to the sides and bottom of the wire bond cavity, the sides of the wire bond cavity provide additional strength to the bond to resist shear and tensile forces that may act on the wire.

Please amend Page 17, Lines 4-8, [Paragraph 0050] as follows:

The first step is to fabricate substrate material [[205]] 405 and form substrate cavity [[210]] 410 in an external surface [[215]] 415 of substrate material [[205]] 405 with restraining edge 425 (step 710). Substrate cavity [[210]] 410 is then filled with portions of wire bond pad [[230]] 430 to form wire bond cavity [[240]] 440 in wire bond pad [[230]] 430 (step 720).

Please amend Page 17, Lines 9-14, [Paragraph 0051] as follows:

Then the edge portions of wire bond pad 430 are covered with passivation material 470 (step 730). Then ball 520 of wire 510 is wirebonded to the sides and bottom of cavity 440 (step 740). A retaining wedge 530 is formed with the portions of ball 520 that fill cavity 440 under restraining wedge 455 (step 750).